



Dynatron R16 Intel Socket 2011 1U Active CPU Cooler

Special Price
\$37.49 was
\$49.99

Product Images



Short Description

Active 1U rackmount CPU cooler from Dynatron® for Intel® LGA 2011 (Socket R) Sandy Bridge server processors. Constructed from copper for optimal heat transfer and sporting vapor chamber technology, the R16 supports a CPU with maximum TDP rating of 150W. Thermal compound is pre-printed with Shin-Etsu G751; no additional thermal compound is required. The R16 features a double ball-bearing, PWM blower for durability and longevity. What is a Vapor Chamber and how does that help me? A vapor chamber is, in essence, a flattened heatpipe in direct contact to the CPU surface that transfers and dissipates heat more efficiently than a traditional heatsink can manage.

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Recommend for Intel® Sandy Bridge - EP / EX Processor, Socket LGA 2011

Specifications

Overall Specification:

- Dimension: 90.0 x 90.0 x 28.0 mm
- Weight: 390g ± 5g
- Material: Vapor Chamber Base with Copper Stacked Fin
- Fin Direction Perpendicular to System Airflow
- Alloy Frame Blower with PWM function
- Convenient Heat Sink Captive Mounting
- Shin-Etsu G751 Thermal Grease Pre-Printed
- Backing Plate is not included
- Support CPU Power up to 150Watts

Blower Specification:

CPU Socket 2011



CPU Support Intel® Sandy Bridge EP/EX Processors



Solution 1U Solution



Overall Dimension 90.0 x 90.0 x 28.0 mm



Weight 390 g



Material Vapor Chamber Base with Copper Stacked Fin



Fan Dimension 80 x 80 x 15 mm



Speed
At Duty Cycle 20%: 1000 RPM
At Duty Cycle 50%: 3500 RPM
At Duty Cycle 100%: 6000 RPM



Bearing 2 Ball Bearing



Rated Voltage 12 V



Power
At Duty Cycle 20%: 0.6 W
At Duty Cycle 50%: 3.84 W
At Duty Cycle 100%: 14.4 W



Air Flow
At Duty Cycle 20%: 6.5 CFM
At Duty Cycle 50%: 11.2 CFM
At Duty Cycle 100%: 19.1 CFM



Noise Level
At Duty Cycle 20%: 21.5 dBA
At Duty Cycle 50%: 43.0 dBA
At Duty Cycle 100%: 55.8 dBA



Air Pressure
At Duty Cycle 20%: 2.27 mm-H2O
At Duty Cycle 50%: 18.56 mm-H2O
At Duty Cycle 100%: 54.5 mm-H2O



Lead Wire Pin Out
Pin1- (-)
Pin2- (+)
Pin3- (Techometer/Signal output)
Pin4- (PWM)



Cooling Performance VS. Airflow (Wind Tunnel Simulation)



Note

1. Support CPU Power up to 150 Watts
2. Pre-print thermal compound Shin-Etsu G751
3. RoHS Compliance
4. Backplate is not included

Additional Information

| | |
|----------------|--------------------------|
| Brand | Dynatron |
| SKU | R16 |
| Weight | 1.5000 |
| Compatibilty | Intel LGA 2011&(-3)/2066 |
| Material | Copper |
| Fan Dimensions | 80mm |
| Fan Connection | 4-Pin PWM |
| Special Price | \$37.49 |

